

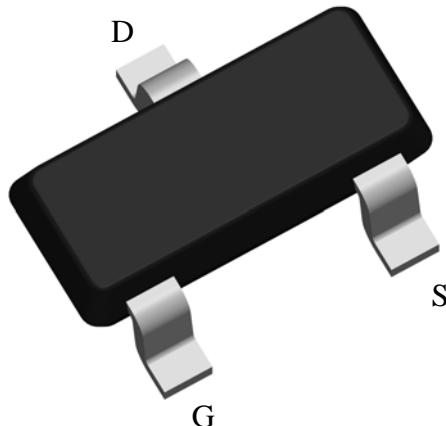
60V N-Channel Enhancement Mode MOSFET

Outline

Features:

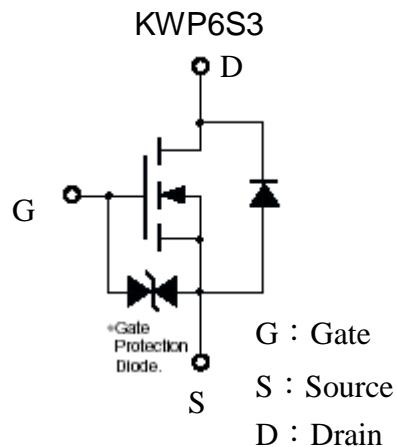
- Simple drive requirement
- Small package outline
- ESD protected gate, $\geq 2\text{kV}$ (HBM)
- Pb-free lead plating and halogen-free package

SOT-323



Symbol

BV_{DSS}	60V
$\text{ID} @ \text{V}_{\text{GS}}=10\text{V}, \text{T}_A=25^\circ\text{C}$	0.24A
$\text{R}_{\text{DS(on)}}(\text{MAX}) @ \text{V}_{\text{GS}}=10\text{V}, \text{ID}=0.5\text{A}$	1.1Ω (typ.)
$\text{R}_{\text{DS(on)}}(\text{MAX}) @ \text{V}_{\text{GS}}=4.5\text{V}, \text{ID}=0.2\text{A}$	1.3Ω (typ.)



Ordering Information

Device	Package	Shipping
KWP6S3	SOT-323 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings ($T_a=25^\circ C$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current @ $V_{GS}=10V$, $T_A=25^\circ C$ (Note 3)	I_D	0.24	A
Continuous Drain Current @ $V_{GS}=10V$, $T_A=70^\circ C$ (Note 3)		0.19	
Pulsed Drain Current (Notes 1, 2)	I_{DM}	0.96	V
ESD susceptibility (Note 4)	V_{ESD}	2000	
Maximum Power Dissipation@ $T_A=25^\circ C$ (Note 3)	P_D	0.2	W
Operating Junction and Storage Temperature	T_j , T_{stg}	-55~+150	$^\circ C$

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient, max (Note 3)	$R_{\theta JA}$	625	$^\circ C/W$
Thermal Resistance, Junction-to-Case, max	$R_{\theta JC}$	250	

Note : 1. Pulse width limited by maximum junction temperature.
 2. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
 3. Surface mounted on copper pad of FR-4 board with minimum footprint, 2 oz. copper.
 4. Human body model, $1.5k\Omega$ in series with $100pF$

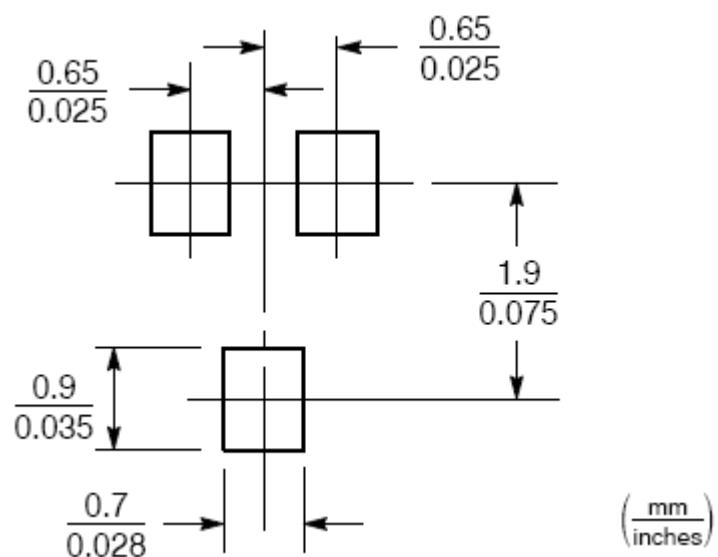
Electrical Characteristics ($T_j=25^\circ C$, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Static						
BV_{DSS}	60	-	-	V	$V_{GS}=0V$, $I_D=250\mu A$	
$\Delta BV_{DSS}/\Delta T_j$	-	0.06	-	V/ $^\circ C$	Reference to $25^\circ C$, $I_D=250\mu A$	
$V_{GS(th)}$	1	-	2.5	V	$V_{DS}=V_{GS}$, $I_D=250\mu A$	
I_{GSS}	-	-	± 10	μA	$V_{GS}=\pm 16V$, $V_{DS}=0V$	
ID_{SS}	-	-	1		$V_{DS}=60V$, $V_{GS}=0V$	
	-	-	10		$V_{DS}=48V$, $V_{GS}=0V$ ($T_j=70^\circ C$)	
$*R_{DS(ON)}$	-	1.1	2.5	\wedge	$I_D=0.5A$, $V_{GS}=10V$	
	-	1.3	3		$I_D=0.2A$, $V_{GS}=4.5V$	
$*G_{FS}$	-	0.25	-	S	$V_{DS}=10V$, $I_D=0.1A$	
Dynamic						
C_{iss}	-	23	-	pF	$V_{DS}=30V$, $V_{GS}=0V$, $f=1MHz$	
C_{oss}	-	7	-			
C_{rss}	-	1	-			
$t_{d(on)}$	-	3.8	-	ns	$V_{DS}=30V$, $I_D=0.5A$, $V_{GS}=10V$, $R_G=1\Omega$	
t_r	-	15.4	-			
$t_{d(off)}$	-	9.8	-			
t_f	-	16.2	-			

Qg	-	1.6	-	nC	V _{DS} =48V, I _D =0.5A, V _{GS} =10V
Qgs	-	0.6	-		
Qgd	-	0.6	-		
Source-Drain Diode					
I _S	-	-	0.24	A	V _{GS} =0V, I _S =0.1A
I _{SM}	-	-	0.96		
*V _{SD}	-	0.8	1.2	V	I _F =0.5A, dI _F /dt=100A/μs
*t _{rr}	-	9.2	-	ns	
*Q _{rr}	-	3	-	nC	

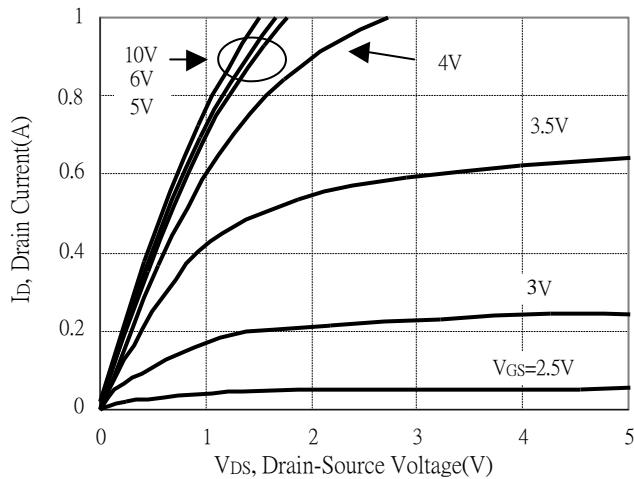
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Recommended Soldering Footprint

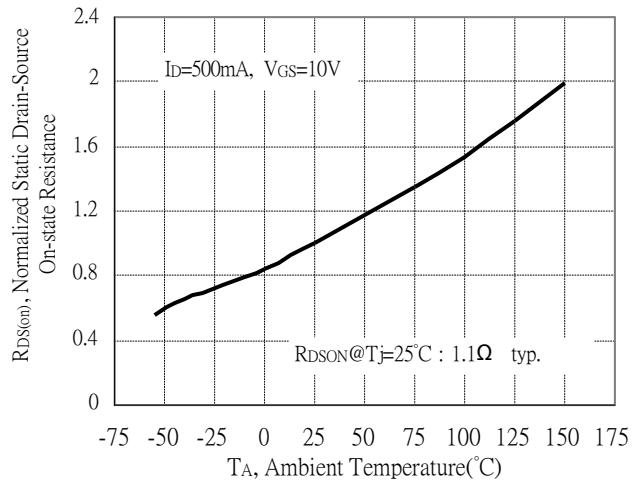


Typical Characteristics

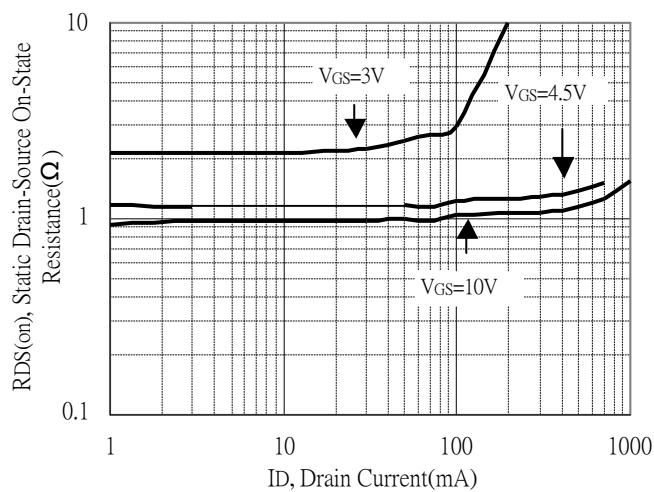
Typical Output Characteristics



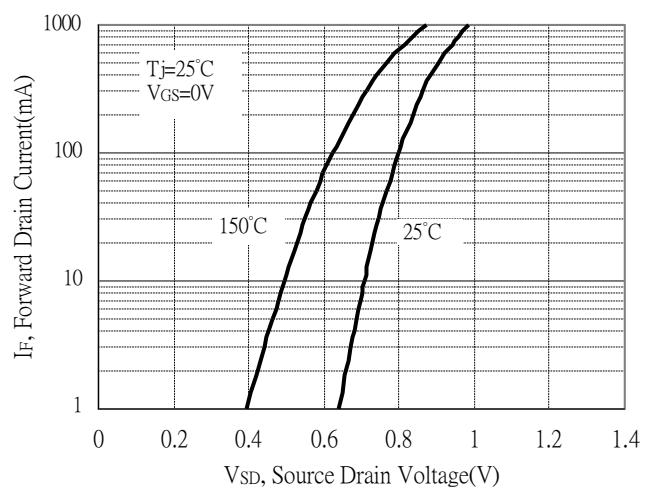
Static Drain-Source On-resistance vs Ambient Temperature



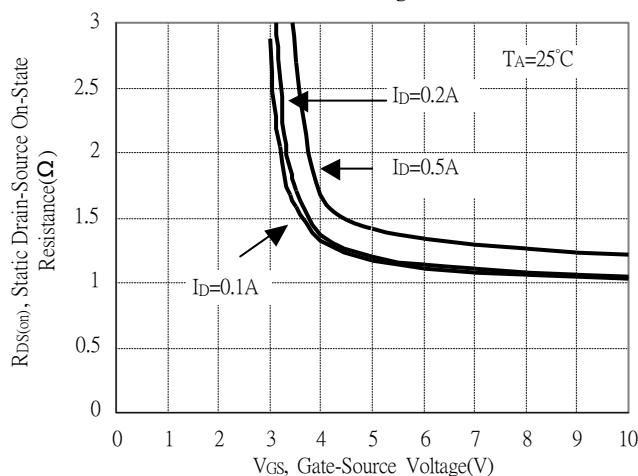
Static Drain-Source On-State resistance vs Drain Current



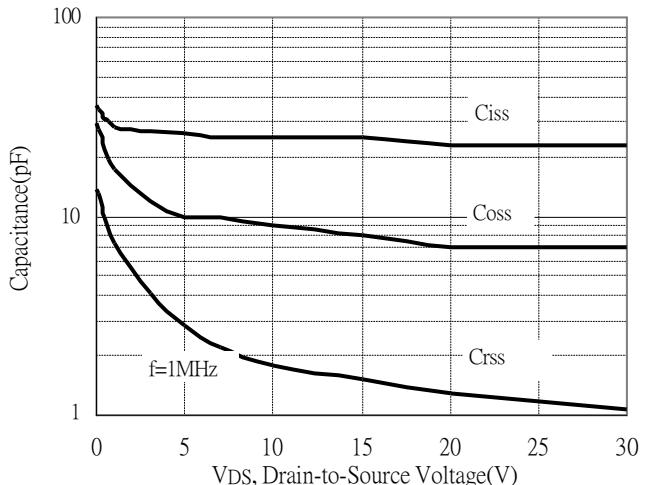
Forward Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

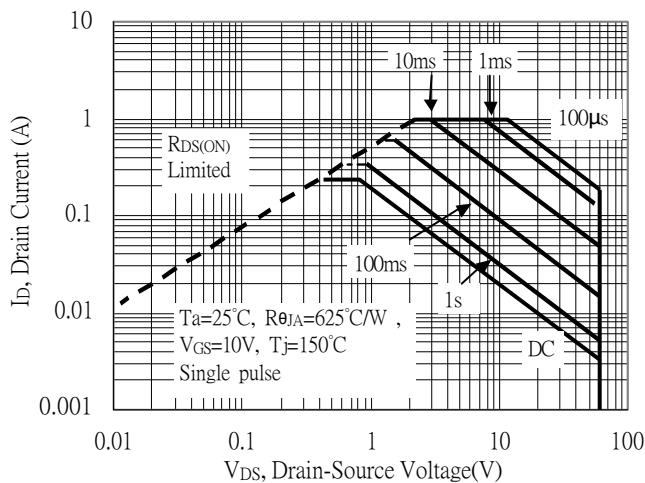


Capacitance vs Reverse Voltage

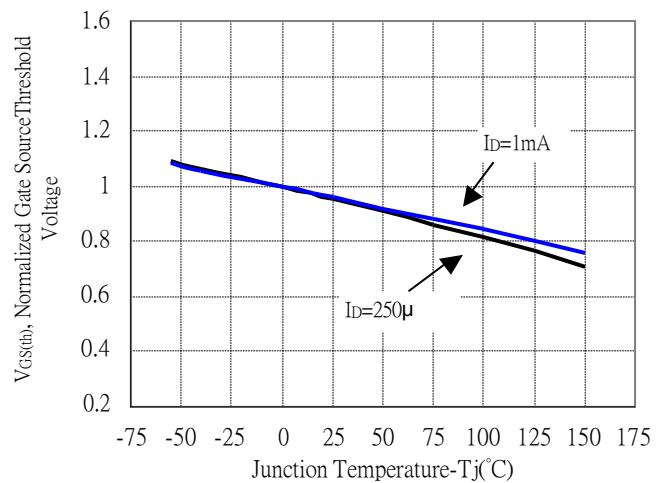


Typical Characteristics(Cont.)

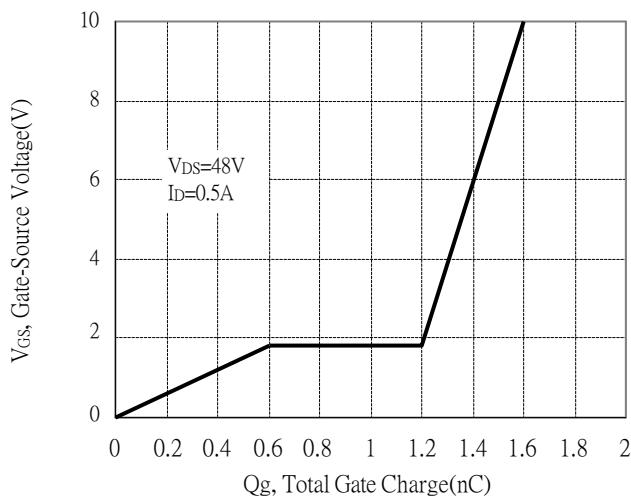
Maximum Safe Operating Area



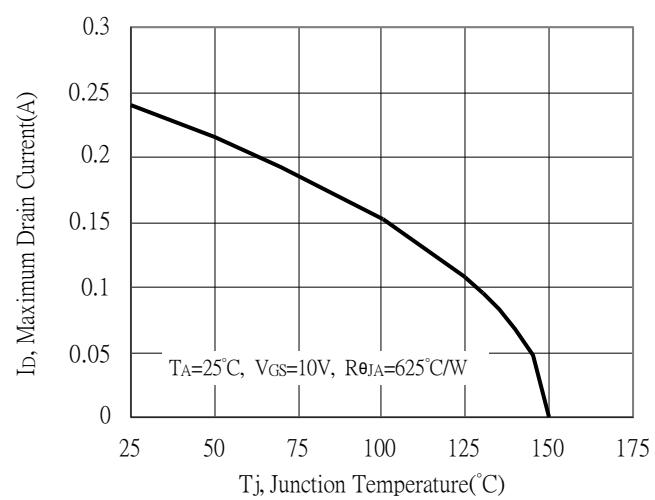
Gate Threshold Voltage vs Ambient Temperature



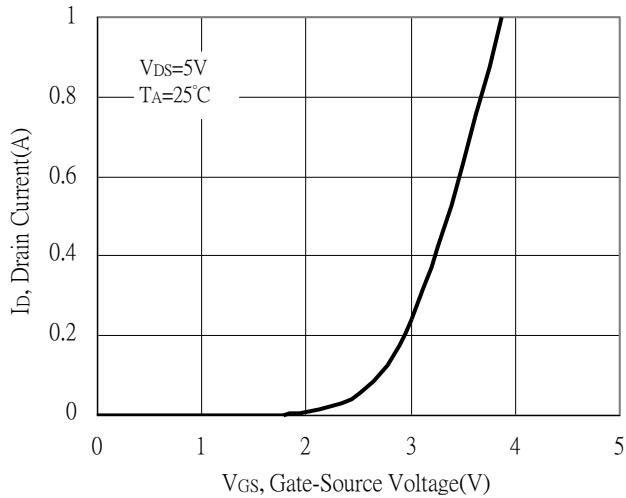
Gate Charge Characteristics



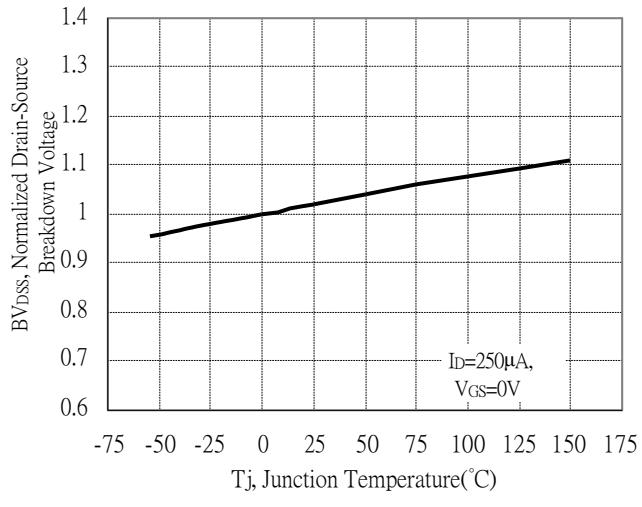
Maximum Drain Current vs Junction Temperature



Drain Current vs Gate-Source Voltage

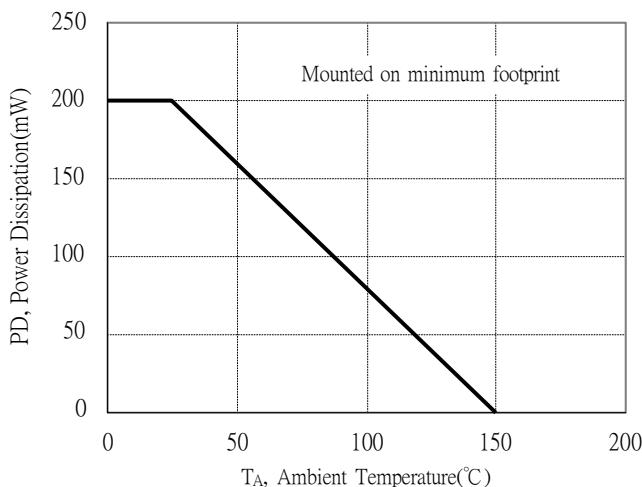


Breakdown Voltage vs Ambient Temperature

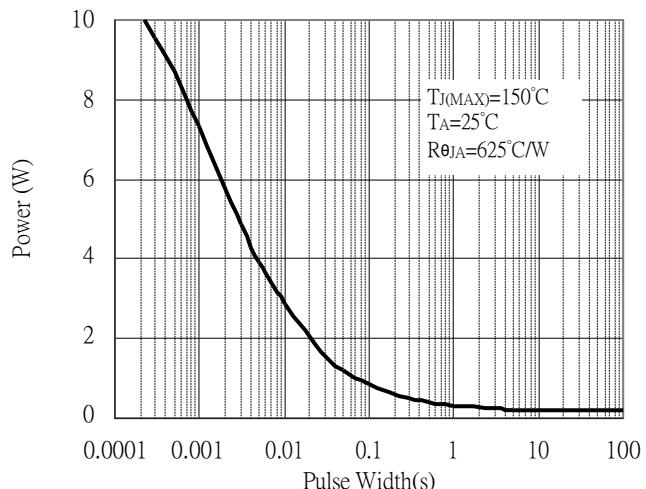


Typical Characteristics(Cont.)

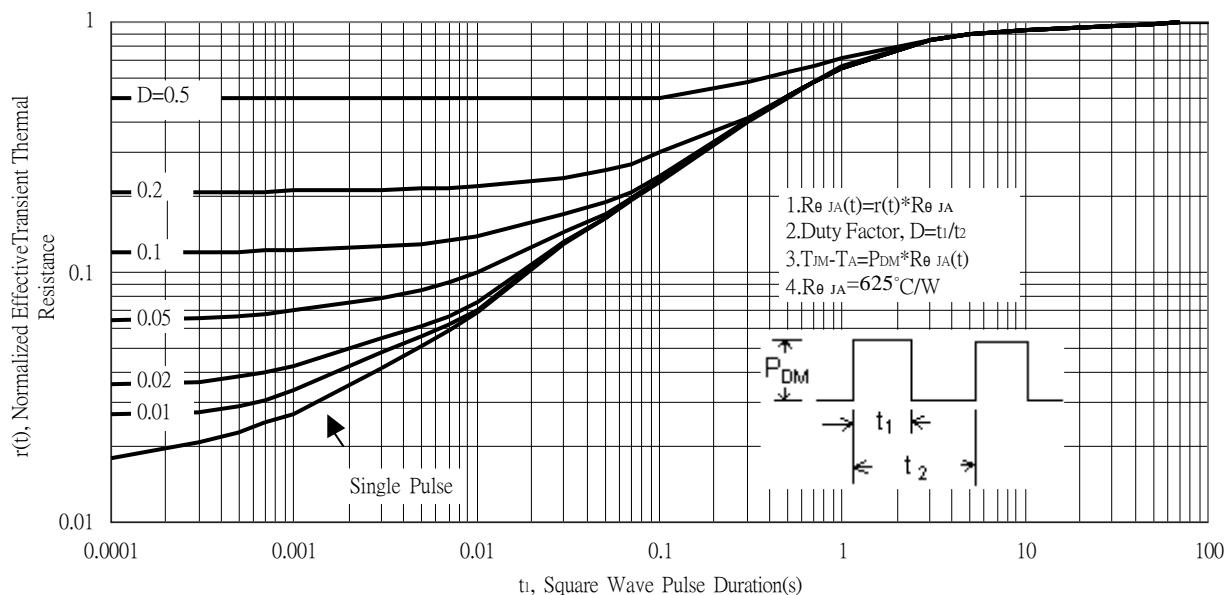
Power Derating Curve



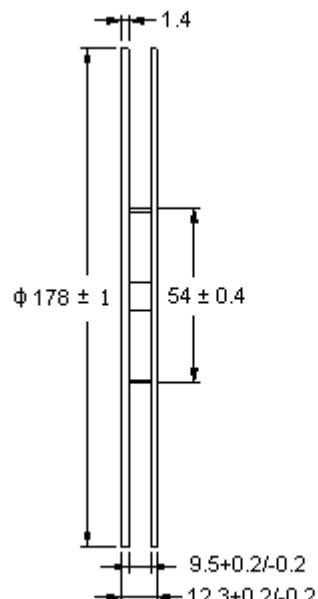
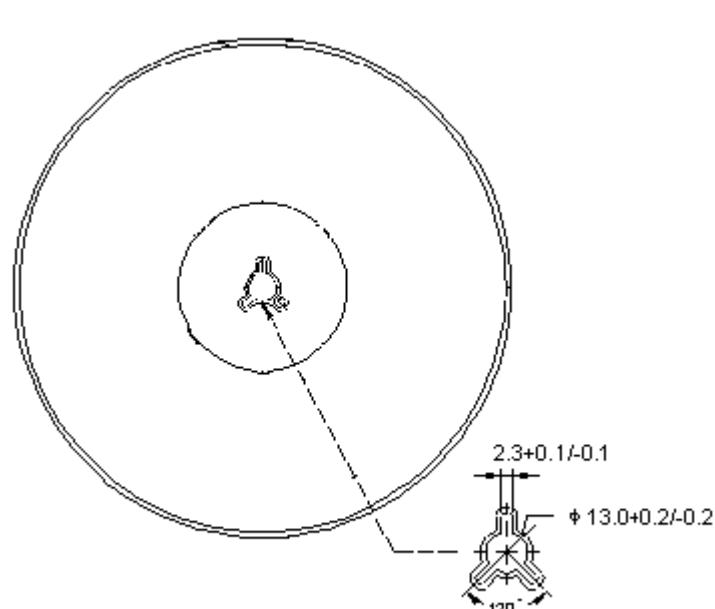
Single Pulse Power Rating, Junction to Ambient



Transient Thermal Response Curves

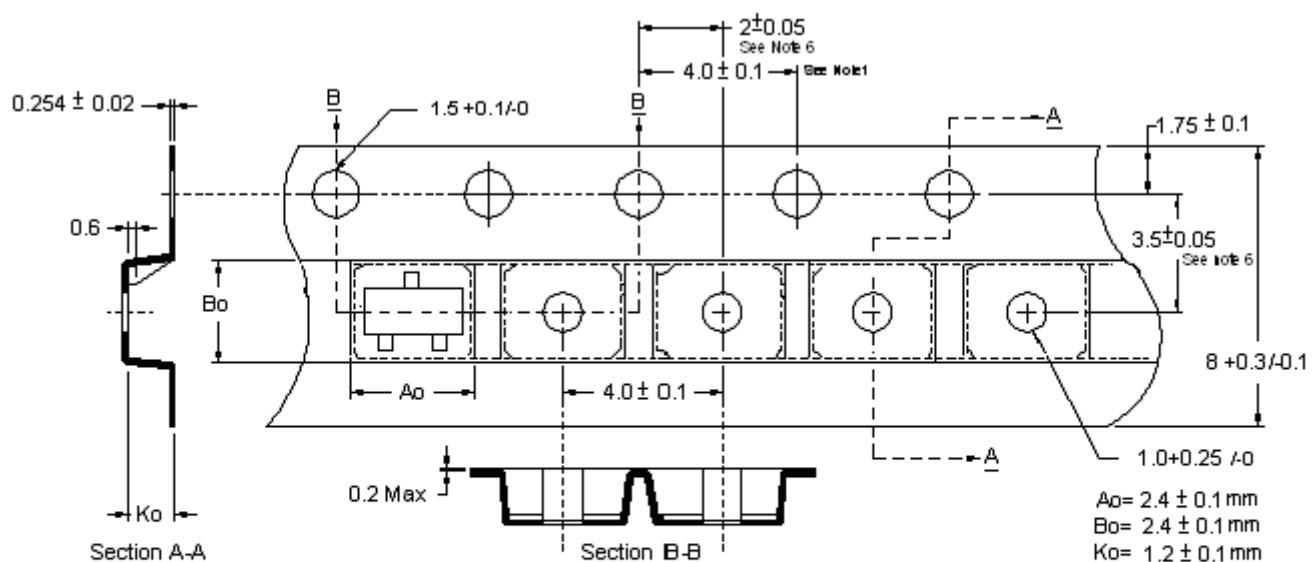


Reel Dimension



Unit: millimeter

Carrier Tape Dimension

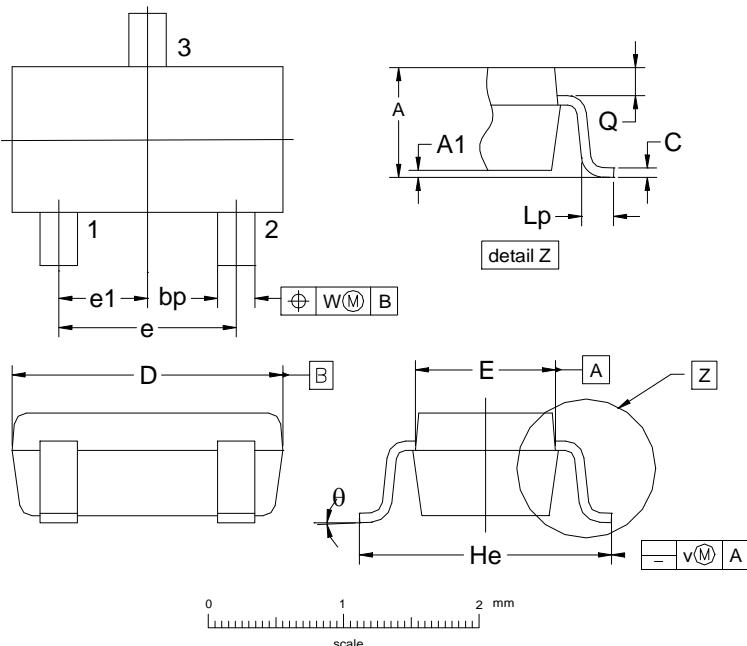


Notes:

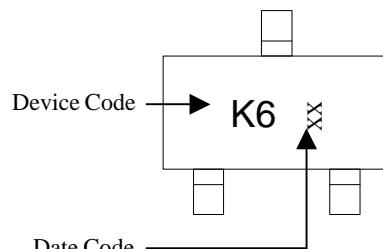
1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material : Conductive black polystyrene.
4. A_o & B_o measured on a plane 0.3mm above the bottom of the pocket.
5. K_o measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

SOT-323 Dimension



Marking:



3-Lead SOT-323 Plastic
Surface Mounted Package
Package Code: S3

Style: Pin 1.Gate 2.Source 3.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0315	0.0433	0.80	1.10	e1	0.0256	-	0.65	-
A1	0.0000	0.0039	0.00	0.10	He	0.0787	0.0886	2.00	2.25
bp	0.0118	0.0157	0.30	0.40	Lp	0.0059	0.0177	0.15	0.45
C	0.0039	0.0098	0.10	0.25	Q	0.0051	0.0091	0.13	0.23
D	0.0709	0.0866	1.80	2.20	v	0.0079	-	0.2	-
E	0.0453	0.0531	1.15	1.35	w	0.0079	-	0.2	-
e	0.0512	-	1.3	-	θ	-	-	10°	0°